

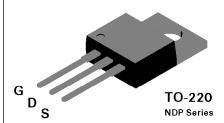
# NDP7060 / NDB7060 N-Channel Enhancement Mode Field Effect Transistor

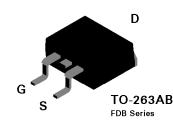
#### **General Description**

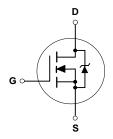
These N-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, high cell density, DMOS technology. This very high density process is especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulses in the avalanche and commutation modes. These devices are particularly suited for low voltage applications such as automotive, DC/DC converters, PWM motor controls, and other battery powered circuits where fast switching, low in-line power loss, and resistance to transients are needed.

#### **Features**

- $\blacksquare$  75A, 60V.  $\mathrm{R_{DS(ON)}} = 0.013\Omega$  @  $\mathrm{V_{GS}} = 10\mathrm{V}.$
- Critical DC electrical parameters specified at elevated temperature.
- Rugged internal source-drain diode can eliminate the need for an external Zener diode transient suppressor.
- 175°C maximum junction temperature rating.
- High density cell design for extremely low R<sub>DS(ON)</sub>.
- TO-220 and TO-263 (D<sup>2</sup>PAK) package for both through hole and surface mount applications.







## Absolute Maximum Ratings T<sub>c</sub> = 25°C unless otherwise noted

Symbol	Parameter	NDP7060	NDB7060	Units	
V <sub>DSS</sub>	Drain-Source Voltage	60		V	
$V_{DGR}$	Drain-Gate Voltage ( $R_{GS} \le 1 \text{ M}\Omega$ )	60		V	
V <sub>GSS</sub>	Gate-Source Voltage - Continuous	±20		V	
	- Nonrepetitive (t <sub>P</sub> < 50 μs)	±			
I <sub>D</sub>	Drain Current - Continuous	75		А	
	- Pulsed	22	25		
P <sub>D</sub>	Maximum Power Dissipation @ T <sub>C</sub> = 25°C	15	150		
	Derate above 25°C	,	1		
T <sub>J</sub> ,T <sub>STG</sub>	Operating and Storage Temperature Range	-65 to	-65 to 175		
T <sub>L</sub>	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds	27	75	°C	

Symbol	Parameter	Conditions		Min	Тур	Max	Units
DRAIN-S	OURCE AVALANCHE RATINGS (Note 1)	·					
W <sub>DSS</sub>	Single Pulse Drain-Source Avalanche Energy	$V_{DD} = 25 \text{ V}, I_{D} = 75 \text{ A}$				550	mJ
I <sub>AR</sub>	Maximum Drain-Source Avalanche Curre	ent				75	Α
OFF CH	ARACTERISTICS						
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_{D} = 250 \mu\text{A}$		60			V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	$V_{DS} = 60 \text{ V}, V_{GS} = 0 \text{ V}$	T <sub>1</sub> = 125°C			250 1	μA mA
I <sub>GSSF</sub>	Gate - Body Leakage, Forward	V <sub>GS</sub> = 20 V, V <sub>DS</sub> = 0 V	[ · j · · = · ·			100	nA
I <sub>GSSR</sub>	Gate - Body Leakage, Reverse	$V_{GS} = -20 \text{ V}, V_{DS} = 0 \text{ V}$				-100	nA
ON CHAI	RACTERISTICS (Note 1)			•		•	
V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$		2	2.8	4	V
Co(u.)			T <sub>J</sub> = 125°C	1.4	2.1	3.6	
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance	$V_{GS} = 10 \text{ V}, I_{D} = 40 \text{ A}$	1 -		0.01	0.013	Ω
		$T_{J} = 125^{\circ}$	T <sub>J</sub> = 125°C		0.015	0.024	]
I <sub>D(on)</sub>	On-State Drain Current	$V_{GS} = 10 \text{ V}, V_{DS} = 10 \text{ V}$		75			Α
g <sub>FS</sub>	Forward Transconductance	$V_{DS} = 10 \text{ V}, I_{D} = 37.5 \text{ A}$		15	39		S
DYNAMI	C CHARACTERISTICS	·					
C <sub>iss</sub>	Input Capacitance	$V_{DS} = 25 \text{ V}, \ V_{GS} = 0 \text{ V},$ $f = 1.0 \text{ MHz}$			2960	3600	pF
C <sub>oss</sub>	Output Capacitance				1130	1600	pF
C <sub>rss</sub>	Reverse Transfer Capacitance				380	800	pF
	NG CHARACTERISTICS (Note 1)						
t <sub>D(on)</sub>	Turn - On Delay Time	$V_{DD} = 30 \text{ V}, \ I_{D} = 75 \text{ A},$ $V_{GS} = 10 \text{ V}, R_{GEN} = 5 \Omega$			17	30	nS
t <sub>r</sub>	Turn - On Rise Time				128	400	nS
t <sub>D(off)</sub>	Turn - Off Delay Time				54	80	nS
t <sub>r</sub>	Turn - Off Fall Time				90	200	nS
$\overline{Q_{g}}$	Total Gate Charge	$V_{DS} = 48 \text{ V},$ $I_{D} = 75 \text{ A}, V_{GS} = 10 \text{ V}$			100	115	nC
$Q_{gs}$	Gate-Source Charge				14.5		nC
$Q_{gd}$	Gate-Drain Charge				51		nC

Symbol	Parameter	Conditions		Min	Тур	Max	Units
DRAIN-S	OURCE DIODE CHARACTERISTICS					II.	
I <sub>s</sub>	Maximum Continuos Drain-Source Diode Forward Current				75	Α	
SM	Maximum Pulsed Drain-Source Diode Forward Current				225	Α	
V <sub>SD</sub>	Drain-Source Diode Forward Voltage	V <sub>GS</sub> = 0 V, I <sub>S</sub> = 37.5 A (Note 1)			0.9	1.3	V
			T <sub>J</sub> = 125°C		0.84	1.2	
t m	Reverse Recovery Time	$V_{GS} = 0 \text{ V}, I_F = 75 \text{ A}, dI_F/dt = 100 \text{ A}$	Vµs	40	76	150	ns
ı <sub>rr</sub>	Reverse Recovery Current			2	4.7	10	Α
THERMA	L CHARACTERISTICS	·					
R <sub>øJC</sub>	Thermal Resistance, Junction-to-Case				1	°C/W	
R <sub>øJA</sub>	Thermal Resistance, Junction-to-Ambient				62.5	°C/W	

Note: 1. Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2.0%.

# **Typical Electrical Characteristics**

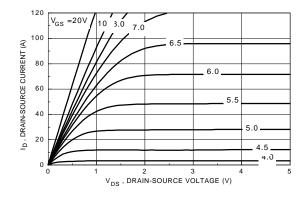
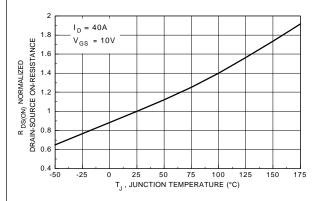


Figure 1. On-Region Characteristics

Figure 2. On-Resistance Variation with Gate Voltage and Drain Current



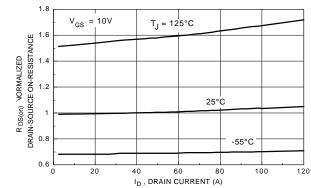
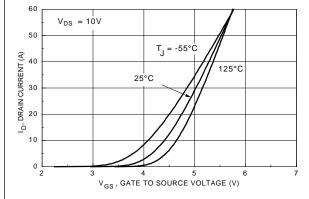


Figure 3. On-Resistance Variation with Temperature

Figure 4. On-Resistance Variation with Drain Current and Temperature



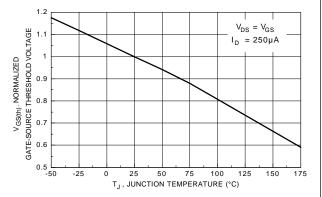


Figure 5. Transfer Characteristics

Figure 6. Gate Threshold Variation with Temperature

# Typical Electrical Characteristics (continued)

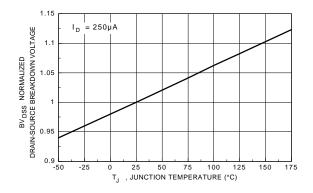


Figure 7. Breakdown Voltage Variation with Temperature

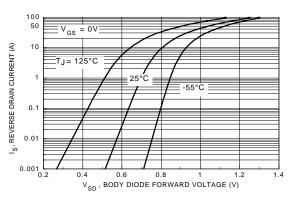


Figure 8. Body Diode Forward Voltage Variation with Current and Temperature

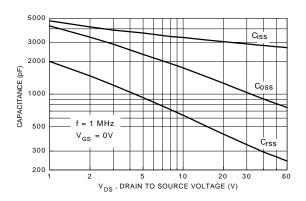


Figure 9. Capacitance Characteristics

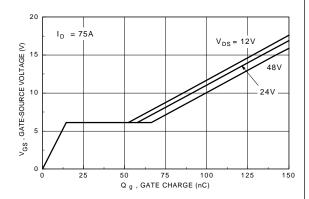


Figure 10. Gate Charge Characteristics

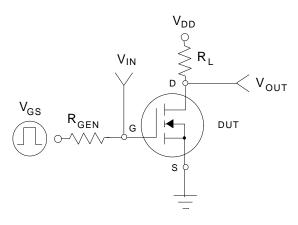


Figure 11. Switching Test Circuit

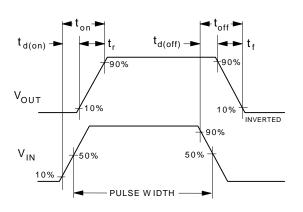
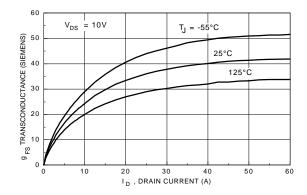


Figure 12. Switching Waveforms

# **Typical Electrical Characteristics (continued)**



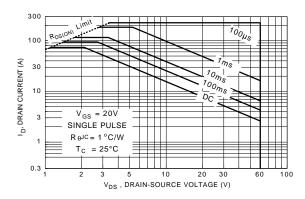


Figure 13. Transconductance Variation with Drain Current and Temperature

Figure 14. Maximum Safe Operating Area

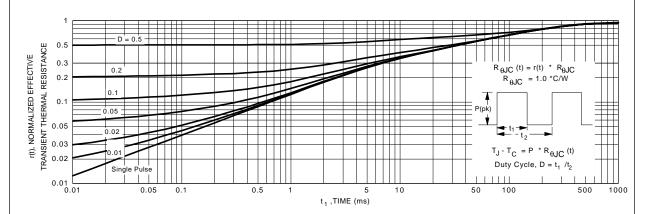


Figure 15. Transient Thermal Response Curve

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